WHAT IS CLAIMED IS:

1. An electronic parts mounting board comprising:

an electrode circuit base member having an electrode on a surface of at least one side;

a projecting electrode bonded to said electrode of said electrode circuit base member;

an insulating member provided on said electrode circuit base member in such a manner as to insulate said electrode of said electrode circuit base member and said projecting electrode; and

a circuit electrode pattern provided on said insulating member and said projecting electrode;

wherein said projecting electrode is formed by forming a specific projecting conductive member at specific positions of said circuit electrode pattern by plating, and pressing said projecting conductive member into said insulating member so as to pass through said insulating member and reach said electrode of said electrode circuit base member.

2. An electronic parts mounting board according to claim 1, wherein said electrode circuit base member is a core member for an inner layer, which has a circuit electrode pattern.

3. An electronic parts mounting board according to

claim 1, wherein said circuit electrode pattern and said projecting electrode are formed by electroplating.

4. An electronic parts mounting board according to claim 1, wherein said circuit electrode pattern is formed by plating gold, nickel, copper, nickel, and gold in this order.

5. An electronic parts mounting board according to claim 1, wherein said projecting electrode is formed by selectively plating copper on said circuit electrode pattern.

6. An electronic parts mounting board according to claim 1, wherein said insulating member is made from a thermosetting resin having an adhesive property.

7. A method of producing an electronic parts mounting board, comprising the steps of:

forming a specific circuit electrode pattern on a surface of one side of a conductive base member to be plated and etched, by plating a specific conductive material thereon;

selectively forming a non-plated material on said circuit electrode board on which said circuit electrode pattern has been formed;

forming a projecting electrode for connection on said circuit electrode pattern by plating a specific

conductive material on said circuit electrode pattern with said non-plated material used as a mask;

before after removing said non-plated material, putting an insulating thermal bonding member between said circuit electrode board and a specific electrode circuit base member, pressing said projecting electrode of said circuit electrode board into said thermal bonding member so as to reach said electrode circuit base member, to bond said circuit electrode board to said electrode circuit base member; and

removing said conductive base member from a multilayer board obtained by bonding said circuit electrode board to said electrode circuit base member by selective etching.

8. A method of producing an electronic parts mounting board according to claim 7, wherein said circuit electrode pattern and said projecting electrode are formed by electroplating, and thicknesses of said circuit electrode pattern and said projecting electrode are controlled by adjusting a plating current.

9. A method of producing an electronic parts mounting board according to claim 7, wherein said circuit electrode pattern is formed by plating nickel, gold, nickel, copper, nickel, and gold in this order on said

conductive base member.

10. A method of producing an electronic parts mounting board according to claim 7, wherein said projecting electrode is formed by selectively plating copper on said circuit electrode pattern.

11. A method of producing an electronic parts mounting board according to claim 7, wherein said electrode circuit base member is a core member for an inner layer, which has a circuit electrode pattern.

12. A method of producing an electronic parts mounting board according to claim 7, wherein said circuit electrode pattern is formed by plating a conductive material on said base member with said non-plated member used as a mask after selectively forming a first non-plated member on said conductive base member.

13. A method of producing an electronic parts mounting board according to claim 12, wherein a sheet-like second non-plated member having a specific opening width is selectively formed on said circuit electrode pattern.

14. A method of producing an electronic parts mounting board according to claim 13, wherein a plurality of sheet-like non-plated members having the specific opening widths sequentially narrowed are selectively

stacked on said second non-plated member.